

ATTY. DOCKET NO. 23587-702

SERIAL NO. 09/437,882

APPLICANT Kosowsky

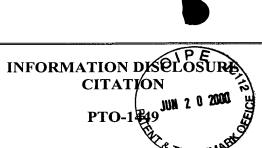
FILING DATE November 10, 1999

GROUP 2811

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	•1	BADEM U.S.	PATENT DOCUMENTS			
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
188	3,685,026	08/15/1972	Wakabayashi, et al.	340	173 R	08/20/1970
188	3,808,576	04/30/1974	Castonguay, et al.	338	309	07/21/1972
129	3,977,957	08/31/1976	Kosowsky, et al.	204	224 R	09/04/1974
MBP	4,405,432	09/20/1983	Kosowsky	204	206	10/22/1982
138	4,642,160	02/10/1987	Burgess	156	630	08/12/1985
160	4,726,991	02/23/1988	Hyatt, et al.	428	329	07/10/1986
13Pal	4,799,128	01/17/1989	Chen	361	414	04/10/1987
NBP.	4,888,574	12/19/1989	Rice, et al.	338	309	03/28/1988
10 Pales	4,892,776	01/09/1990	Rice	428	209	09/02/1987
18 Pal	4,928,199	05/22/1990	Diaz, et al.	361	56	09/11/1989
189	4,935,584	06/19/1990	Boggs	174	262	05/24/1988
188	4,977,357	12/11/1990	Shrier	338	21	01/11/1988
vsl	5,068,634	11/26/1991	Shrier	338	21	08/08/1989
IBP	5,092,032	03/03/1992	Murakami	29	830	05/15/1991
188	5,095,626	03/17/1992	Kitamura, et al.	29	827	08/10/1989
rBC	5,099,380	03/24/1992	Childers, et al.	361	56	04/19/1990
186	5,142,263	08/25/1992	Childers, et al.	338	21	02/13/1991
BP	5,148,355	09/15/1992	Lowe, et al.	361	410	10/22/1990
186	5,189,387	02/23/1993	Childers, et al.	338	20	07/11/1991
1BS	5,246,388	09/21/1993	Collins, et al.	439	620	06/30/1992
10805	5,248,517	09/28/1993	Shrier, et al.	427	58	11/15/1991
18Pubs	5,252,195	10/12/1993	Kobayashi, et al.	205	126	10/28/1992
1959 •	5,282,312	02/01/1994	DiStefano, et al.	29	830	12/31/1991
188	5,295,297	03/22/1994	Kitamura, et al.	29	827	07/20/1992
(BP	5,300,208	04/05/1994	Angelopoulos, et al.	205	50	08/14/1989
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	U.S. PATENT DOCUMENTS						
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING	DATE
188	5,317,801	06/07/1994	Tanaka, et al.	29	830	01/29/1	993
18-81	5,347,258	09/13/1994	Howard, et al.	338	333	04/07/1	993
188	5,367,764	11/29/1994	DiStefano, et al.	29	830	12/31/1	991
IBP	5,404,637	04/11/1995	Kawakami	29	843	04/30/1	993
188	5,481,795	01/09/1996	Hatakeyama, et al.	29	852	06/10/1	994
IBP	5,487,218	01/30/1996	Bhatt, et al.	29	852	11/21/1	994
188	5,502,889	04/02/1996	Casson, et al.	29	830	01/08/1	993
165	5,654,564	08/05/1997	Mohsen	257	209	01/31/1	996
IBP	5,708,298	01/13/1998	Masayuki, et al.	257	723	12/10/1	996
188	5,734,188	03/31/1998	Murata, et al.	257	401	07/01/1	996
168	5,744,759	04/28/1998	Ameen, et al.	174	260	05/29/1	996
IBP	5,807,509	09/15/1998	Shrier, et al.	252	512	04/21/1	997
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18 Pepus	5,906,042	05/25/1999	- Lan, et al.	29	852	10/04/1	995
18 Palar	5,910,685	06/08/1999	- Watanabe, et al.	257	777	12/03/1	997
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0 4/2	WO 96/02944	02/01/1996	PCT	H01L	23/525	YES	NO
18901	WO 96/02944 WO 96/02924	02/01/1996	PCT	H01C			
(BROLE)				 			
18 Pall	WO 97/26665	07/24/1997	PCT	H01C			
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INFORMATION DISCLOSURE **CITATION**

PTO-1449

ATTY. DOCKET	NO.
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APPLICANT Lex Kosowsky

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1BRober	4,113,899	9-12-78	Henry et al.	427	290	5-23-77	
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EXAMINER'S	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	TRANSL	LATION
INITIALS						YES	NO
18 Polo	WO 96/02922	01/02/96	PCT	H01C			
1B Palm	CH 663 491 A5	15/12/87	Switzerland	H01L	23/14		\boxtimes
100100	1					1	I .

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	OTHER DOC	CUMENTS (I	ncluding Author, Title, Da	te, Pertinent Pa	ges, Etc.)		
1BBal-	Susumu T "Lat	minated Sheet a	and Manufacture of Electric o. 243, 7 June 1989 (JP0104	Wiring Circuit	Using the Same	', Patent	
1BJDD							
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Attorney Docket No.: 23587-702

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INFORMATION DISCOOSURE CITATION		23587-702	09/437,882			
	PTO-1449 JUN 2 0 2000 E	APPLICANT Kosowsky				
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,BP	Reimann; "Method for Forming a High Density Printed Wiring Board"; May 27, 1986; Pat. No. 4,591,411 156/634; abstract					
1BP	Bruckner, et al.; "Two-layer 174/255; abstract.	Bruckner, et al.; "Two-layer or Multilayer Printed Circuit Board"; January 3, 1995; Pat. No. 5,378,858; 174/255; abstract.				
188	Felcman, et al.; "Extended Card Edge Connector and Socket"; April 4, 1995; Pat. No. 5,403,208; 439/633; abstract.					
188	Yoshida, et al.; "Process for Producing Printed Wiring Board"; March 26, 1996; Pat. No. 5,501,350; 216/20; abstract.					
IBP	Alpaugh, et al.; "Method of Making Printed Circuit Board"; November 11, 1997; Pat. No. 5,685,070; 29/840; abstract.					
1858	Kobayashi, et al.; "Method of Finishing a Printed Wiring Board with a Soft Etching Solution and a Preserving Treatment or a Solder-Leveling Treatment"; September 8, 1998; Pat. No. 5,802,714; 29/852; abstract.					
188	Ferry, et al.; "Method and Apparatus for forming Fine Patterns on Printed Circuit Board"; November 10, 1998; Pat. No. 5,834,160; 430/313; abstract.					
IBP .	Yurchenco, et al.; "Processor Card Assembly Having a Cover with Flexible Locking Latches"; January 5, 1999; Pat. No. 5,856,910; 361/704; abstract.					
186	Khandros, et al.; "Method of Stacking Electronic Components"; July 27, 1999; Pat. No. 5,926,951; 29/843; abstract.					
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